

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Chee Kiang Yew, et al.**

Art Unit (parent case): **2812**

Serial No.: **TBD**

Examiner (parent case): **Lattin, C.W.**

Filed: **Herewith**

Docket: **TI-26239.1**

For: **Direct Attachment of Semiconductor
Chip to Organic Substrate**

Conf. No.: **TBD**

TRANSMITTAL OF FORMAL DRAWINGS

Commissioner For Patents
Attn: Official Drafts Person
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner For Patents, Alexandria, VA 22313-1450.


Elizabeth Austin

 2/2/2007
Date

Dear Sir:

Submitted herewith are 2 sheets of formal drawings.

The enclosed drawings are being provided in a timely manner therefore no additional fee is required.

Texas Instruments Incorporated
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Dallas, Texas 75265
(972) 917-5653

Respectfully submitted,



Michael K. Skrehot
Attorney for Applicants
Reg. No.: 36,682